

AMENDMENTS TO THE SPECIFICATION:

Please amend the specification at page 1, line 3 as follows:

~~Description~~ CROSS-REFERENCE TO RELATED APPLICATIONS

This application claims the benefit under 35 U.S.C. §365 International Application Serial No. PCT/EP2003/014319, filed December 16, 2003, the entire contents of which are incorporated by reference herein.

BACKGROUND OF THE INVENTION

1. Field of the Invention

Please add the following heading to the specification at page 1, line 7:

2. Description of Related Art

Please amend the paragraph beginning at page 2, line 16 as follows:

BRIEF SUMMARY OF THE INVENTION

The object of a fast and accurate track following is accomplished amazingly simply by a read-write head according to ~~claim 1~~ the present disclosure, as well as a process for data recording and retrieval according to ~~claim 23~~ the present disclosure and a process for fabricating a read-write head according to ~~claim 28~~ the present disclosure, whereby a new approach according to the invention is taken by integrating a magnetic micropositioner or microactuator into the slider. ~~Advantageous refinements are presented in the respective subclaims.~~

Please amend the paragraph beginning at page 12, line 5:

~~It is depicted by:~~ BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS

Please add the following heading to the specification at page 12, line 30:

DETAILED DESCRIPTION OF THE INVENTION

Please amend the paragraph beginning at page 19, line 27 as follows:

In Fig. 10A, a first wafer 36 with a first block 11 is depicted. On this wafer, the build up of the spring system and the carrier for the read-write chip as well as the magnetic flux closure or the magnetizable elements of the electromagnetic actuator devices is accomplished.

Please amend the paragraph beginning at page 20, line 1 as follows:

Block 11 in wafer 36 is separated in three virtual sections 112, 113, and 114. Furthermore, a sacrificial layer 363 is present on a first side 361 of the wafer 36, or, respectively, the block 11 and carrier 14 embedded therein. Preferably, the sacrificial layer comprises a silica layer. On this side 361, the leaf springs 12 and 13 are deposited, whereat the leaf springs are connecting the first section 112 with the further section 113. Preferably, a silicon wafer is used as the first wafer.